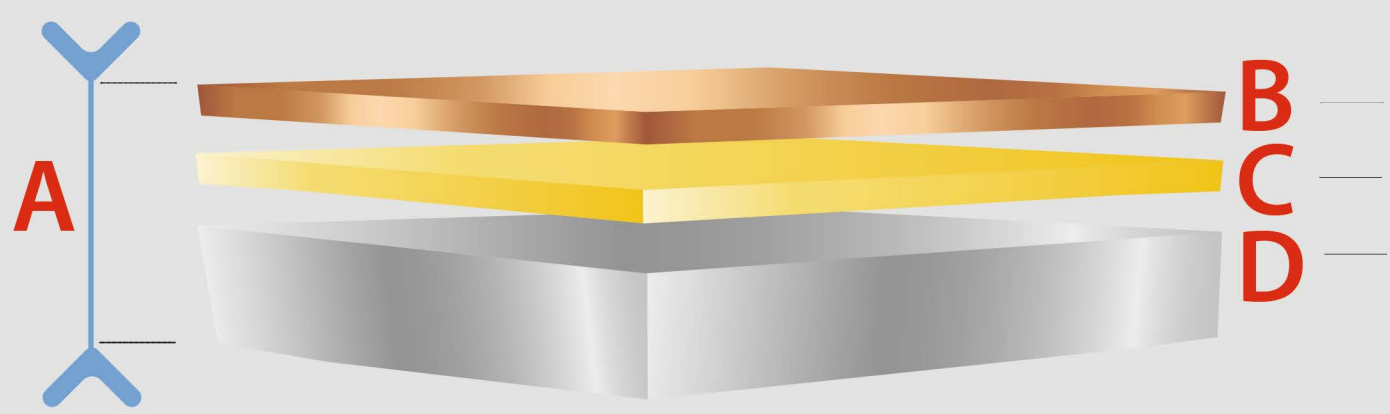
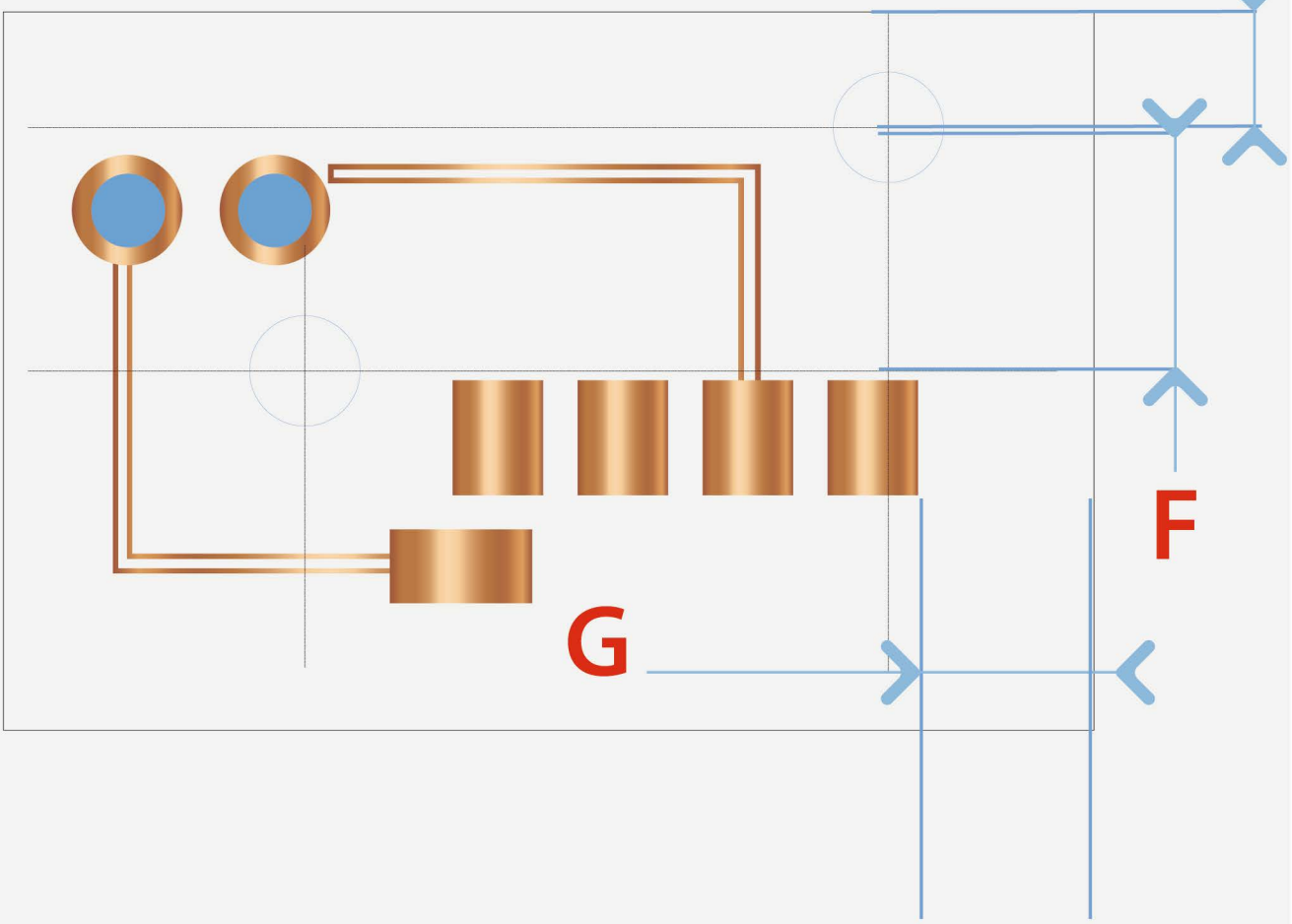
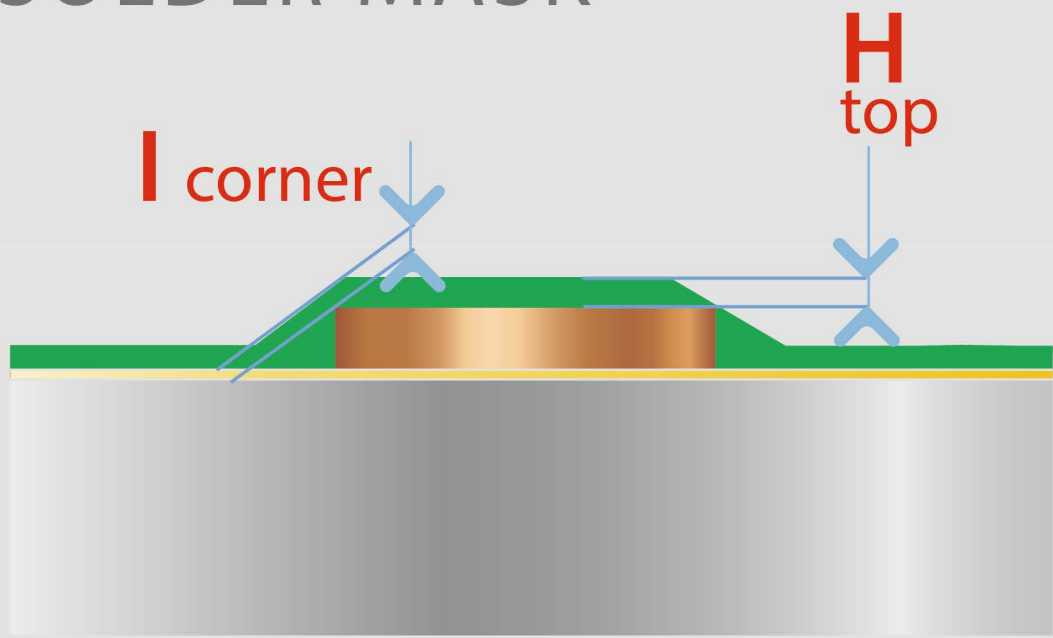
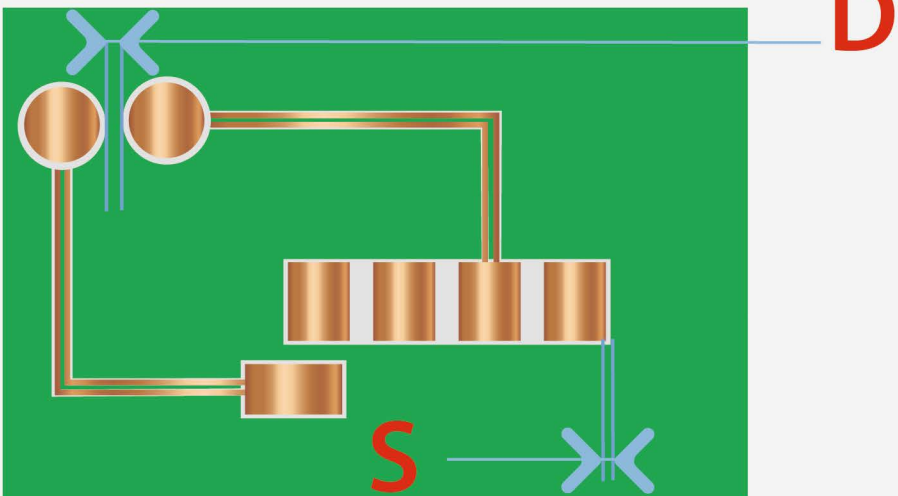
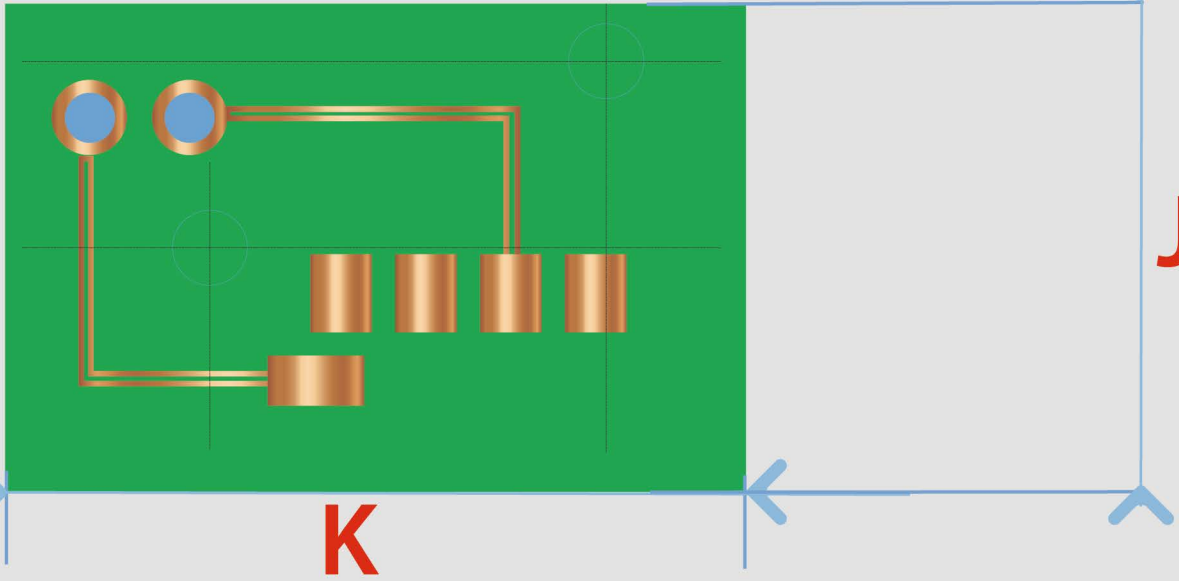
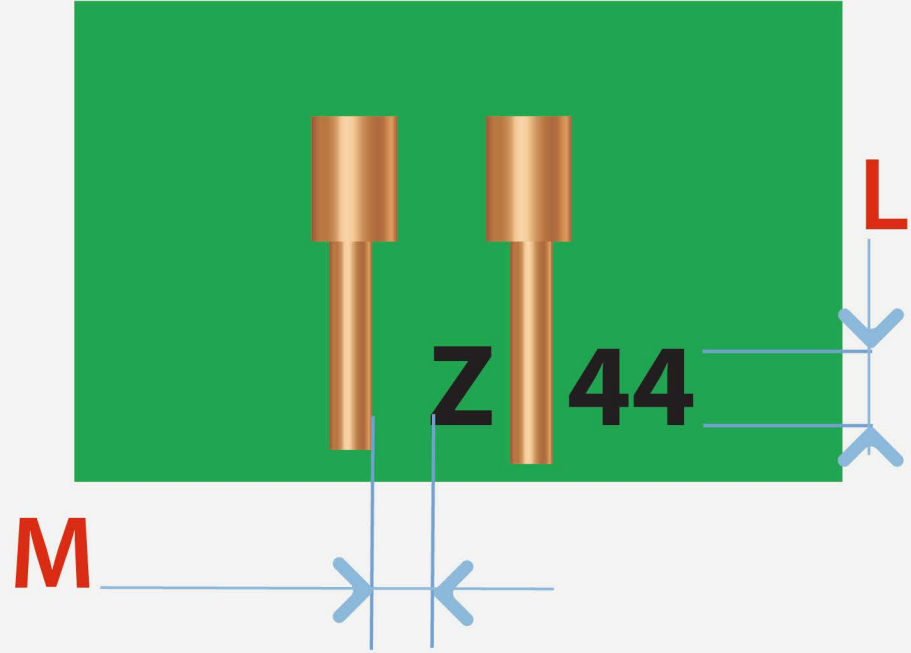
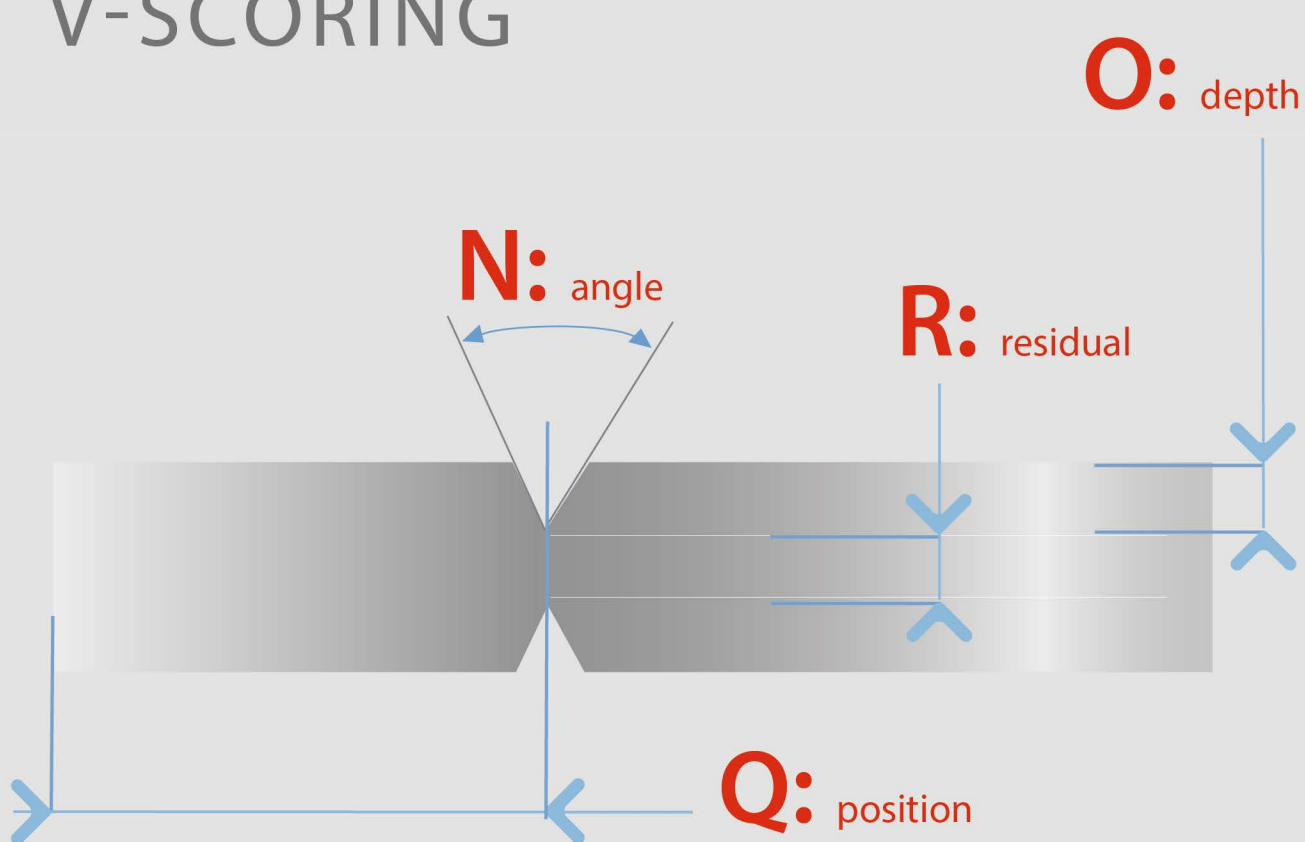
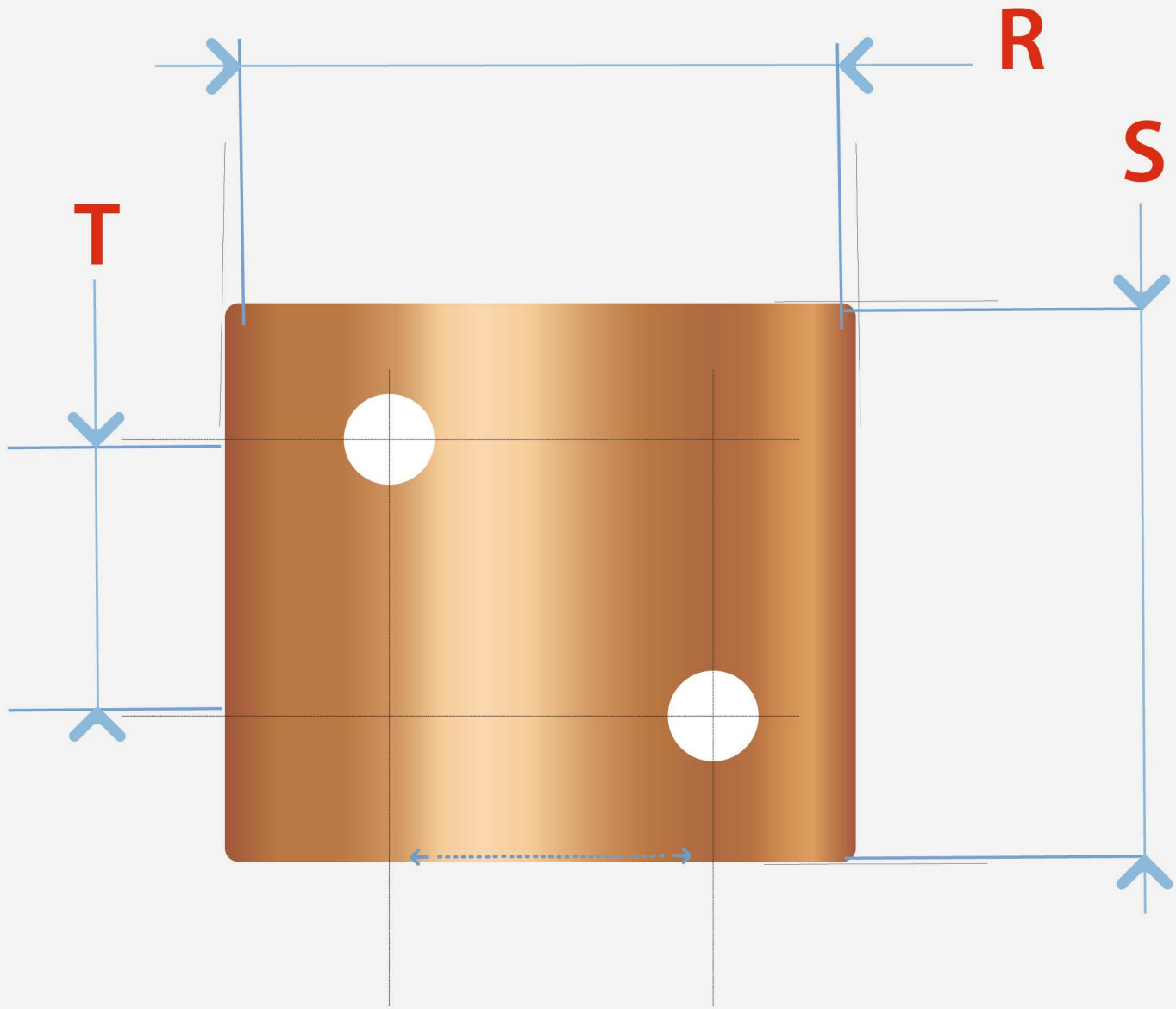


# IMS TECHNOLOGY

INSULATED METAL SUBSTRATE - IMS PCB				
ITEM DESIGN RULES	SYMBOL	DESCRIPTION	STANDARD	ADVANCED
		_____ Total thickness	_____ 0.30 - 3.00 mm	_____ Up to 6.0 mm
		_____ Copper	_____ 1 oz - 3 oz	_____ 6 oz
		_____ Dielectric		
		_____ Aluminum	_____ 0.5 mm - 3 mm	_____ 4 mm
		Depending on the raw material supplier & customer needs	0.038 - 0.2 mm	
		Depending on the raw material supplier & customer needs	1 – 12 W:m°K	
METAL BOARD THICKNESS				
DIELECTRIC LAYER THICKNESS				
THERMAL CONDUCTIVITY				
BREAKDOWN VOLTAGE		Depending on the raw material supplier & customer needs	6 KV AC	
LAYER COUNT		Maximum Layer Count	1 to 6	Up to 8 Layers
COPPER THICKNESS	B	Single sided & ML MCPCB	1-6 Oz	1 - 10 Oz
CIRCUIT WIDTH & SPACING		W/S 1 OZ 2 OZ 3 OZ 4 OZ 6 OZ	125/125 µm 150/150 µm 200/200 µm 250/250 µm 300/300 µm	100/100 µm 125/150 µm 150/200 µm 200/250 µm 250/300 µm
DRILLING	E F G 	Hole position tolerance =< 6.35mm  Hole to hole tolerance  Hole to outline tolerance (routing)	+/- 0.075 mm  +/- 0.2 mm  +/- 0.05 mm	+/- 0.05 mm  +/- 0.15 mm  +/- 0.05 mm



# IMS TECHNOLOGY

ITEM DESIGN RULES	SYMBOL	DESCRIPTION	STANDARD	ADVANCED
	H I	Solder Mask	15 µm	15 µm
		Thickness	7 µm	7 µm
	S SPACE D DAM	Minimum clearance		
		Opening	100 µm	75 µm
		Dam	100 µm	75 µm
SOLDER MASK 	J K	Outline	+/- 0.2 mm	+/- 0.15 mm
SOLDER MASK 		Tolerance	+/- 0.2 mm	+/- 0.15 mm
ROUTING 	L M	Text width	0.2 mm	0.1 mm
LEGEND 		Legend/ Copper clearance	0.2 mm (minimum)	0.15 mm (minimum)
V-SCORING 	R S T U	Length	+/- 0.15 mm	+/- 0.10 mm
PUNCHING 		Width	+/- 0.15 mm	+/- 0.10 mm
		A	+/- 0.15 mm	+/- 0.10 mm
		B	+/- 0.15 mm	+/- 0.10 mm
		Hole Diameter	+/- 0.15 mm	+/- 0.10 mm
		Radius	+/- 0.05 mm	+/- 0.05 mm